

PAD TEMPERATURE ADJUSTMENT MECHANISM FOR ADJUSTING
TEMPERATURE OF POLISHING PAD, AND POLISHING DEVICE

ABSTRACT

[Problem] one object of the present invention is to provide a pad temperature adjustment mechanism which contributes to at least one of exchange of a polishing pad and elimination of thermal contact between a polishing pad and a pad temperature adjustment means.

[Solution] A pad temperature adjustment mechanism for adjusting the temperature of a polishing pad of a polishing device, including: a heat conduction part for conducting heat between the heat conduction part and the polishing pad; an arm that extends from the heat conduction part, wherein a distal end of the arm is formed in a tapered shape; an arm mount for installing the arm, wherein an arm guide having a tapered groove shape corresponding to the shape of the arm is formed in the arm mount; and a falling prevention member for preventing the arm from falling out of the arm guide.

[Selected Drawing] Fig. 8B